

Title (en)  
Method and apparatus for transferring wafers in a wafer processing facility

Title (de)  
Verfahren und Vorrichtung zum Umladen von Scheiben in eine Anlage zum Behandeln von Scheiben

Title (fr)  
Procédé et appareil pour transférer des plaquettes dans une installation de traitement de plaquettes

Publication  
**EP 0810632 A3 19980610 (EN)**

Application  
**EP 97108253 A 19970521**

Priority  
US 65437096 A 19960528

Abstract (en)  
[origin: US6201998B1] An apparatus, method and medium is provided for increasing the efficiency with which wafers are transferred among different processing chambers in a wafer processing facility. A multi-slot cooling chamber allows multiple wafers to be cooled while other wafers are subjected to processing steps in other chambers. Each wafer in the processing sequence is assigned a priority level depending on its processing stage, and this priority level is used to sequence the movement of wafers between chambers. A look-ahead feature prevents low-priority wafer transfers from occurring if such transfers would occur just prior to the scheduling of a high-priority wafer transfer.

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**H01L 21/00**

IPC 8 full level  
**B65G 49/07** (2006.01); **G06Q 10/06** (2012.01); **H01L 21/00** (2006.01); **H01L 21/677** (2006.01)

CPC (source: EP US)  
**G06Q 10/06** (2013.01 - EP US); **H01L 21/67167** (2013.01 - EP US); **H01L 21/67276** (2013.01 - EP US); **H01L 21/67745** (2013.01 - EP US); **Y10S 414/136** (2013.01 - EP US); **Y10S 414/137** (2013.01 - EP US); **Y10S 414/138** (2013.01 - EP US); **Y10S 414/139** (2013.01 - EP US); **Y10S 414/14** (2013.01 - EP US); **Y10S 414/141** (2013.01 - EP US); **Y10T 29/53087** (2015.01 - EP US)

Citation (search report)

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DOCDB simple family (application)  
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